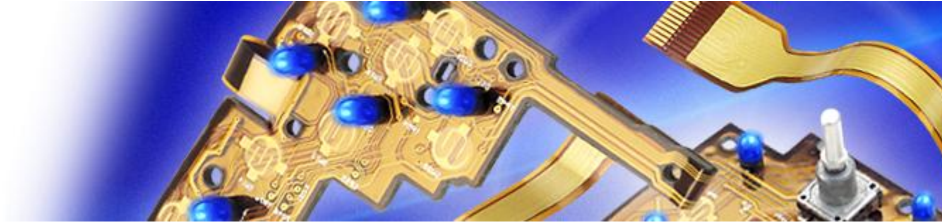

Component Attach Materials

Reference	Status	Conductive filler	Application method	Description	Typical Junction Resistance	Polymer	Nominal Cure
PF504	Sustaining	Ag	Stencil or Dispense	Polysolder ICA for SMD attach	<30 mΩ	Thermoset	140°C / 10min Soak
PF505	Released	Ag	Stencil or Dispense	Polysolder ICA for SMD attach with wider cure window	<30 mΩ	Thermoset	110-140°C / 5-20min Soak
PF506	Released	Au spheres	Stencil or Dispense	ACA developed for flip chip assembly	<100 mΩ	Thermoset	140°C / 30sec bond
PF508	Released	Au spheres	Dispense	Heat activated ACA for thermal compression bonding of flex circuit to Flex, PCB or LCD	<100 mΩ	Thermoplastic	100-110°C / 5-10min dry 153°C / 30sec bond
PF509	Released	Sn/Pb	Stencil	Tin lead solder paste for SMD attach to copper kapton	<10 mΩ	NA	210-220°C Reflow
PF204	Released	NA	Dispense	Strain relief encapsulant applied to SMD junctions to facilitate tight bend radius	NA	Thermoset	UV

Parlex Corporation
1 Parlex Place
Methuen MA 01844 USA

www.parlex.com
flexcircuits@parlex.com
(978) 685-4341